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(54) **PRINTED CIRCUIT BOARD**

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(57) **ABSTRACT**

A printed circuit board includes: a first board unit including a first insulating layer having a first via hole, a first wiring layer disposed on or in the first insulating layer, and a first via including a first metal layer substantially filling the first via hole; and a second board unit including a second insulating layer having a second via hole, a second wiring layer disposed on or in the second insulating layer, and a second via including a second metal layer substantially filling the second via hole. The second board unit is disposed on the first board unit, the second wiring layer has a higher wiring density than that of the first wiring layer, and the second metal layer has a plating structure different from that of the first metal layer.

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